TOP VIEW

SIDE VIEW

BOTTOM VIEW

RECOMMENDED

MOUNTING FOOTPRINT For additional information on our Pb-Free strategy and soldering details, please download the DN Seniconductor Soldering and Mounting Techniques Reference Manual, SILLDERRND.

2X p5

10X L

0.10 C A B

DETAIL B

В

PLATED

SEATING

**PLANE** 

巾

NOTE 3

PLATED SURFACE SURFACE

8X

L3

-A1

PIN ONE — REFERENCE

// 0.10 C

□ 0.08 C NOTE 4

PACKAGE DUTLINE

8X0.25

## WDFNW10 2.5x1.0, 0.5P

CASE 515AH **ISSUE B** 

SECTION C-C

DETAIL A

EXPOSED

PLATED

SURFACE

DETAIL B

**DATE 03 AUG 2020** 

-A3

L3

ALTERNATE CONSTRUCTION

ALTERNATE CONSTRUCTION

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
- DIMENSION 6 APPLIES TO PLATED TERMINALS AND IS MEASURED BETWEEN
- THIS DEVICE CONTAINS WETTABLE FLANK DESIGN FEATURES TO AID IN FILLET FORMATION ON THE LEADS DURING MOUNTING.

	MILLIMETERS			
DIM	MIN.	N□M.	MAX.	
Α	0.70	0.75	0.80	
A1	0.00		0.05	
A3	0.20 REF			
Α4	0.10			
b	0.15	0.20	0.25	
b2	0.35	0.40	0.45	
D	2.40	2.50	2.60	
Е	0.90	1.00	1.10	
e	0.50 BSC			
L	0.30	0.35	0.40	
L3			0.10	

## NOTES:

- CONTROLLING DIMENSION: MILLIMETERS
- 0.15 AND 0.30MM FROM THE TERMINAL TIP.
- COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS			
DIM	MIN.	N□M.	MAX.	
Α	0.70	0.75	0.80	
A1	0.00		0.05	
A3	0.20 REF			
Α4	0.10	-		
ھ	0.15	0.20	0.25	
8	0.35	0.40	0.45	
D	2.40	2.50	2.60	
E	0.90	1.00	1.10	
ω	0.50 BSC			
L	0.30	0.35	0.40	
L3			0.10	

## **GENERIC MARKING DIAGRAM\***



XX = Specific Device Code = Date Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may

not follow the Generic Marking.

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